

L Number	Hits	Search Text	DB	Time stamp
-	42	"thinned chip" or "thinned chips"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 17:56
-	2	5268065.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:49
-	10	"824301"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 15:17
-	3964	"smart card" and chip\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:14
-	1607	"smart card" with chip\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:28
-	189	("smart card" with chip\$1).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:29
-	13	("4511796"   "4714980"   "4789776"   "4822988"   "4825283"   "5048179"   "5049728"   "5081520"   "5155068"   "5526233"   "5703755"   "5965867"   "5991159").PN.	USPAT	2003/10/24 14:40
-	13	("4511796"   "4714980"   "4789776"   "4822988"   "4825283"   "5048179"   "5049728"   "5081520"   "5155068"   "5526233"   "5703755"   "5965867"   "5991159").PN.	USPAT	2003/10/24 14:48
-	2	5192682.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:50
-	2	6137687.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 15:18
-	13	("4511796"   "4714980"   "4789776"   "4822988"   "4825283"   "5048179"   "5049728"   "5081520"   "5155068"   "5526233"   "5703755"   "5965867"   "5991159").PN.	USPAT	2003/10/24 15:23
-	46	4511796.URPN.	USPAT	2003/10/24 15:29
-	225	("chip card" or "chip cards").ti.	USPAT	2003/10/24 16:19
-	1	5122481.pn.	USPAT	2003/11/14 14:18
-	141	lintec.as.	USPAT	2003/11/14 13:32
-	30	lintec.as. and 156/\$.cccls.	USPAT	2003/11/14 13:33
-	2996	156/344 or 156/584	USPAT	2003/11/14 13:33
-	109	(156/344 or 156/584) and (dissolv\$3 with (adhesive or glue))	USPAT	2003/11/14 13:34

-	42	(156/344 or 156/584) and (dissolv\$3 with (adhesive or glue)) and (semiconductor\$1 or wafer\$1)	USPAT	2003/11/14 13:36
-	8	(156/344 or 156/584) and (dissolv\$3 with (adhesive or glue)) and (semiconductor\$1 or wafer\$1) and dic\$3	USPAT	2003/11/14 14:07
-	35	5110388.URPN.	USPAT	2003/11/14 14:03
-	109	(dissolv\$3 with (adhesive or glue)) and (semiconductor\$1 or wafer\$1) and dic\$3	USPAT	2003/11/14 14:42
-	7	(dissolv\$3 with (adhesive or glue)) and (semiconductor\$1 or wafer\$1) and dic\$3	USOCR	2003/11/14 14:11
-	3	"9948137"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/14 14:21
-	14	(wafer\$1 with thinning) with ((dicing or separating) with (chip\$1))	USPAT	2003/11/14 14:26
-	7	(wafer\$1 with thinning) with ((dicing or separating) with (chip\$1))	EPO; JPO; DERWENT; IBM_TDB	2003/11/14 14:26
-	537	438/464	USPAT	2003/11/14 14:43
-	24	438/464 and (dissolv\$3 with (adhesive or glue))	USPAT	2003/11/14 14:47
-	5	438/464 and (dissolv\$3 with (adhesive or glue))	USOCR	2003/11/14 14:47
-	17646	card with chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 17:56
-	5109	(card with chip with (circuit\$2 or conductive))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 17:57
-	11	card with chip with conductive with path	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 18:01
-	0	card with "thinned chip"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 18:01
-	15	card with thinned with chip\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 18:01
-	7	"thinned chip"	USPAT	2003/12/31 18:07
-	17	"thinned chip"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 18:11
-	558	(156/\$.ccls. or 235/\$.ccls.) and (chip\$1 with thin\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 18:12
-	145	(156/\$.ccls. or 235/\$.ccls.) and (chip\$1 near2 thin\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 18:15

-	62	(156/\$.ccls. or 235/\$.ccls.) and (chip\$1 near2 thin\$4) and card\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 18:22
-	14594	print\$3 with coil	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 18:23
-	1147	print\$3 with coil with (inductive or conductive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 18:23
-	72	(print\$3 near4 (coil near1 (inductive or conductive)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 18:27
-	3420	156/344 or 156/584	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 18:27
-	394	(156/344 or 156/584) and chip\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 18:27
-	24	(156/344 or 156/584) and chip\$1 and (dissolv\$3 with adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 18:33
-	1487	156/344.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 18:34
-	1216	156/344.ccls.	USPAT	2003/12/31 18:37
-	438	156/344.ccls. and (adhesive with (double or two or "2" or second))	USPAT	2003/12/31 18:37
-	2	stromberg with michael	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 22:52
-	2062	wafer\$1 with thin\$3 with (divid\$3 or separat\$3 or dic\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 22:53
-	1673	wafer\$1 with thin\$3 with (divid\$3 or separat\$3 or dic\$3)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 22:55
-	521	(wafer\$1 with thin\$3 with (divid\$3 or separat\$3 or dic\$3)).ab.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 22:59
-	28	5268065.URPN.	USPAT	2004/03/18 22:57
-	89	(wafer\$1 with thin\$3 with (divid\$3 or separat\$3 or dic\$3)).ti.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 23:02
-	89	(wafer\$1 with thin\$3 with (divid\$3 or separat\$3 or dic\$3)).ti.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 23:15

-	153	(wafer\$1 with (thinned or thinning)).ti.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 23:31
-	42	(wafer\$1 with (thinned or thinning)).ti. and (dic\$3 or divid\$3 or separat\$3)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 23:31
-	30	(thinned with chip) and ("smart card" or "smart cards")	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 23:29
-	12	(thinned near3 (chip\$1 or die\$1)) and ("smart card" or "smart cards")	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 23:28
-	32	"thinned chip" or "thinned chips"	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 23:30
-	0	(wafer\$1 with (thinned or thinning)).ti. and (dic\$3 or divid\$3 or separat\$3) and (smart with card\$1)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 23:31
-	4	(wafer\$1 with (thinned or thinning)).ti. and (smart with card\$1)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 23:32
-	2	5192682.pn, .	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 23:32
-	9	5192682.URPN.	USPAT	2004/03/18 23:33
-	26	"221470"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/06 22:42
-	13	"2221470"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/06 22:42
-	41	5110388.URPN.	USPAT	2004/05/06 22:57
-	15	"4433846"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/07 09:50
-	40	"smart card" and (thin\$4 near2 chip\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/07 10:07
-	19	card\$1 with (thinned with chip\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/07 11:03
-	3796	miyamoto and hitachi	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/07 11:03
-	23	(miyamoto and hitachi) and thinned	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/07 11:07

-	6	"6224095"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/07 11:05
-	10	"603514"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/07 11:07
-	3	6342434.URPN.	USPAT	2004/05/07 14:53
-	7	("3861978"   "4339297"   "5155068"   "5238876"   "5268065"   "5877034"   "5897337").PN.	USPAT	2004/05/07 14:55
-	45	5155068.URPN.	USPAT	2004/05/07 14:58
-	9	("smart card" or "smart cards") and (lacquer\$3 with protect\$3)	USPAT	2004/05/10 11:36
-	16	lacquer\$3 with protect\$3 with chip\$1	USPAT	2004/05/10 10:50
-	1	6193163.pn.	USPAT	2004/05/10 11:00
-	37	("4889980"   "4890197"   "4931853"   "4990759"   "4997791"   "5018051"   "5048179"   "5121294"   "5134773"   "5173840"   "5184209"   "5192682"   "5208450"   "5232532"   "5244840"   "5250341"   "5335145"   "5346576"   "5387306"   "5480842"   "5510074"   "5585618"   "5671525"   "5725819"   "5837992"   "5852289"   "5876536"   "5952713"   "5955021"   "5969951"   "5996897"   "6019284"   "6025054"   "6036099"   "6036797"   "6066231"   "6073856").PN.	USPAT	2004/05/10 11:31
-	290	("smart card" or "smart cards") and (chip\$1 with surface)	USPAT	2004/05/10 11:36
-	13	("smart card" or "smart cards") and (chip\$1 with surface with flush)	USPAT	2004/05/10 11:39
-	5	("smart card" or "smart cards") and (press\$3 with chip\$1 with surface with flush)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 11:44
-	35	("smart card" or "smart cards") and (press\$3 with chip\$1 with surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 13:20
-	2	"9852772"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 11:56
-	3	"19617621"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 11:57
-	5	provost and solaic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 13:20
-	1	"1981111"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 14:09

-	3	"1981212"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/05/10 14:09
-	2	stromberg and wafer	USPAT	2004/05/10 14:10
-	9	stromberg and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/05/10 14:10
-	658	(dissolv\$3 with adhesive) and (wafer\$1 or semiconductor\$1)	USPAT	2004/05/10 14:14
-	298	(dissolv\$3 near2 adhesive) and (wafer\$1 or semiconductor\$1)	USPAT	2004/05/10 14:14
-	110	(dissolv\$3 with adhesive) and (wafer\$1 or semiconductor\$1) and (dic\$3)	USPAT	2004/05/10 14:14
-	74	(dissolv\$3 with adhesive) and (wafer\$1 or semiconductor\$1) and (dic\$3) and thin\$4	USPAT	2004/05/10 14:14
-	6	("4722130"   "5110388"   "5118567"   "5762744"   "5888883"   "6558975").PN.	USPAT	2004/05/10 16:02
-	34	(US-5762744-\$ or US-4878991-\$ or US-6046073-\$ or US-5268065-\$ or US-6554193-\$ or US-6193163-\$ or US-5155068-\$ or US-4511796-\$ or US-5192682-\$ or US-6105873-\$ or US-5677524-\$ or US-4701600-\$ or US-5122481-\$ or US-5110388-\$ or US-6297076-\$ or US-6007920-\$ or US-5882956-\$ or US-5411921-\$ or US-6642127-\$ or US-6342434-\$ or US-6013534-\$ or US-6412701-\$ or US-5786988-\$ or US-6656819-\$ or US-5994205-\$).did. or (US-20020134842-\$ or US-20020069952-\$ or US-20010040186-\$).did. or (EP-824301-\$ or WO-9948137-\$ or WO-9721243-\$ or FR-2780534-\$).did. or (EP-824301-\$ or DE-19601391-\$).did.	USPAT; US-PGPUB; EPO; DERWENT	2004/05/10 16:03
-	1	(US-3152939-\$).did.	USOCR	2004/05/10 16:03
-	0	((US-5762744-\$ or US-4878991-\$ or US-6046073-\$ or US-5268065-\$ or US-6554193-\$ or US-6193163-\$ or US-5155068-\$ or US-4511796-\$ or US-5192682-\$ or US-6105873-\$ or US-5677524-\$ or US-4701600-\$ or US-5122481-\$ or US-5110388-\$ or US-6297076-\$ or US-6007920-\$ or US-5882956-\$ or US-5411921-\$ or US-6642127-\$ or US-6342434-\$ or US-6013534-\$ or US-6412701-\$ or US-5786988-\$ or US-6656819-\$ or US-5994205-\$).did. or (US-20020134842-\$ or US-20020069952-\$ or US-20010040186-\$).did. or (EP-824301-\$ or WO-9948137-\$ or WO-9721243-\$ or FR-2780534-\$).did. or (EP-824301-\$ or DE-19601391-\$).did.) and thin44	USPAT; US-PGPUB; EPO; DERWENT	2004/05/10 16:03

-	26	((US-5762744-\$ or US-4878991-\$ or US-6046073-\$ or US-5268065-\$ or US-6554193-\$ or US-6193163-\$ or US-5155068-\$ or US-4511796-\$ or US-5192682-\$ or US-6105873-\$ or US-5677524-\$ or US-4701600-\$ or US-5122481-\$ or US-5110388-\$ or US-6297076-\$ or US-6007920-\$ or US-5882956-\$ or US-5411921-\$ or US-6642127-\$ or US-6342434-\$ or US-6013534-\$ or US-6412701-\$ or US-5786988-\$ or US-6656819-\$ or US-5994205-\$).did. or (US-20020134842-\$ or US-20020069952-\$ or US-20010040186-\$).did. or (EP-824301-\$ or WO-9948137-\$ or WO-9721243-\$ or FR-2780534-\$).did. or (EP-824301-\$ or DE-19601391-\$).did.) and thin\$4	USPAT; US-PGPUB; EPO; DERWENT	2004/05/10 16:03
-	26	((US-5762744-\$ or US-4878991-\$ or US-6046073-\$ or US-5268065-\$ or US-6554193-\$ or US-6193163-\$ or US-5155068-\$ or US-4511796-\$ or US-5192682-\$ or US-6105873-\$ or US-5677524-\$ or US-4701600-\$ or US-5122481-\$ or US-5110388-\$ or US-6297076-\$ or US-6007920-\$ or US-5882956-\$ or US-5411921-\$ or US-6642127-\$ or US-6342434-\$ or US-6013534-\$ or US-6412701-\$ or US-5786988-\$ or US-6656819-\$ or US-5994205-\$).did. or (US-20020134842-\$ or US-20020069952-\$ or US-20010040186-\$).did. or (EP-824301-\$ or WO-9948137-\$ or WO-9721243-\$ or FR-2780534-\$).did. or (EP-824301-\$ or DE-19601391-\$).did.) and thin\$4	USPAT; US-PGPUB; EPO; DERWENT	2004/05/10 16:20
-	6	("4722130"   "5110388"   "5118567"   "5762744"   "5888883"   "6558975").PN.	USPAT	2004/05/10 16:07
-	11	"475259"	USPAT; US-PGPUB; EPO; DERWENT	2004/05/10 16:26
-	6	("4722130"   "5110388"   "5118567"   "5762744"   "5888883"   "6558975").PN.	USPAT	2004/05/10 16:24
-	0	6656819.URPN.	USPAT	2004/05/10 16:25
-	3	"9925019"	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/05/10 16:27
-	5	"63164336"	IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/05/11 10:25
-	2118	lintec.as.	IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/05/11 11:52
-	3	"63148655"	IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/05/11 10:26
-	492	156/344.ccls. and 156/584.ccls.	IBM TDB USPAT	2004/05/11 11:38
-	112	(156/344.ccls. and 156/584.ccls.) and (semiconductor\$1 or wafer\$1)	USPAT	2004/05/11 11:38

-	414	lintec.as. and (semiconductor\$1 or wafer\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 11:52
-	203	lintec and (semiconductor\$1 or wafer\$1) and (grind\$3 or thin\$4 or polish\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 11:53
-	76	lintec and (semiconductor\$1 or wafer\$1) and (grind\$3 or thin\$4 or polish\$3) and (die or dice)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 12:03
-	6	("4722130"   "5762744"   "5989982"   "6054372"   "6083811"   "6297131").PN.	USPAT	2004/05/11 12:00
-	1148	GIESECKE and DEVRIENT	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 12:03
-	22	(GIESECKE and DEVRIENT) and semiconductor\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 12:05
-	31	(GIESECKE and DEVRIENT) and (semiconductor\$1 or wafer\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:05
-	10	"624341"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 12:12
-	5	"5912185"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 12:13
-	7	"981156"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 12:14
-	3	"6465330"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 12:14
-	5	("4756968"   "5714029"   "5888883"   "6126772"   "6312800").PN.	USPAT	2004/05/11 12:15
-	33	4756968.URPN.	USPAT	2004/05/11 12:16
-	1	6083811.pn.	USPAT	2004/05/11 12:38
-	48	"dicing film" with adhesive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 14:37
-	5	"10231602"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 14:41



-	23789	((wafer\$1 or semiconductor\$1) with (grind\$3 or thin\$4)).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/05/11 14:42
-	946	((wafer\$1 or semiconductor\$1) with (grind\$3 or thin\$4)).ti.	USPAT	2004/05/11 14:42
-	93	((wafer\$1 or semiconductor\$1) with (grinding or thinning or thinned)).ti.	USPAT	2004/05/11 15:02
-	10306	"19921230"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/05/11 15:03
-	1	"19921230" and haghiri	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/05/11 15:05
-	591	haghiri	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/05/11 15:05
-	86	(GIESECKE and DEVRIENT) and haghiri	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/05/11 15:05
-	6	(GIESECKE and DEVRIENT) and haghiri and (semiconductor\$1 or wafer\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/05/11 15:05
-	10311	"19921230"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/08/11 20:49
-	1	"19921230".pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/08/11 20:49
-	6	"19811115"	USPAT	2004/08/11 21:07
-	1521	"19811115"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/08/11 21:07
-	2	"19811115".pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/08/11 21:07
-	0	"19812120"	USPAT	2004/08/11 21:32
-	0	"19812120".pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/08/11 21:32
-	0	"19812120".pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/08/11 21:33

-	3542	156/584 or 156/344	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 21:39
-	573	(156/584 or 156/344) and (semiconductor\$1 or wafer\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 21:41
-	322	(156/584 or 156/344).ccls. and (semiconductor\$1 or wafer\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 21:41
-	56	card\$1.ti. and (chip\$1 with (exterior or external\$2) with surface)	USPAT	2004/08/20 20:50
-	20	card\$1.ti. and (chip\$1 with (exterior or external\$2) with surface with (circuit\$2 or coil))	USPAT	2004/08/20 20:50
-	10	"824301"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/20 20:16
-	48	card\$1.ti. and (chip\$1 with (exterior or external\$2) with surface) and (circuit\$2 or coil)	USPAT	2004/08/20 20:57
-	28	(card\$1.ti. and (chip\$1 with (exterior or external\$2) with surface) and (circuit\$2 or coil)) not (card\$1.ti. and (chip\$1 with (exterior or external\$2) with surface with (circuit\$2 or coil)) )	USPAT	2004/08/20 20:50
-	24	card\$1.ti. and (chip\$1 with (exterior or external\$2) with surface) and ((circuit\$2 or coil) with print\$3)	USPAT	2004/08/20 20:57
-	4	"6412701" AND PRINT\$3	USPAT	2004/08/22 22:14